

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

Additions to claims are underlined and deletions from claims are presented in ~~strikethrough~~ text.

26. An RFID device comprising:

a first electrical component having

a first electrically conductive contact;

a second electrical component having

a second electrically conductive contact;

wherein the first and second electrically conductive contacts are in alignment

with one another;

at least one electrically conductive hard particle attached to at least one of the first and second electrically conductive contacts,

wherein the at least one electrically conductive hard particle has a hardness at least as great as that of at least one of the first and second electrically conductive contacts;

a non-conductive adhesive disposed between the first and second electrically conductive contacts;

wherein the first and second electrically conductive contacts are held together by the non-conductive adhesive once the adhesive cures;

wherein a permanent electrical connection is formed between the first and second electrically conductive contacts; and

wherein a permanent physical attachment is formed between the first electrical component and the second electrical component.

59. The method of claim 47 49 or 57, wherein the at least one electrically conductive hard particle is attached to the first electrically conductive contact by an electroless metal-particle co-deposition process.

71. The electrical component of claim 70, wherein the chip further comprises at least one of the following: a discrete circuit device, an integrated circuit device, a memory device, a microprocessor device, a transceiver device, and an electro-optic device.